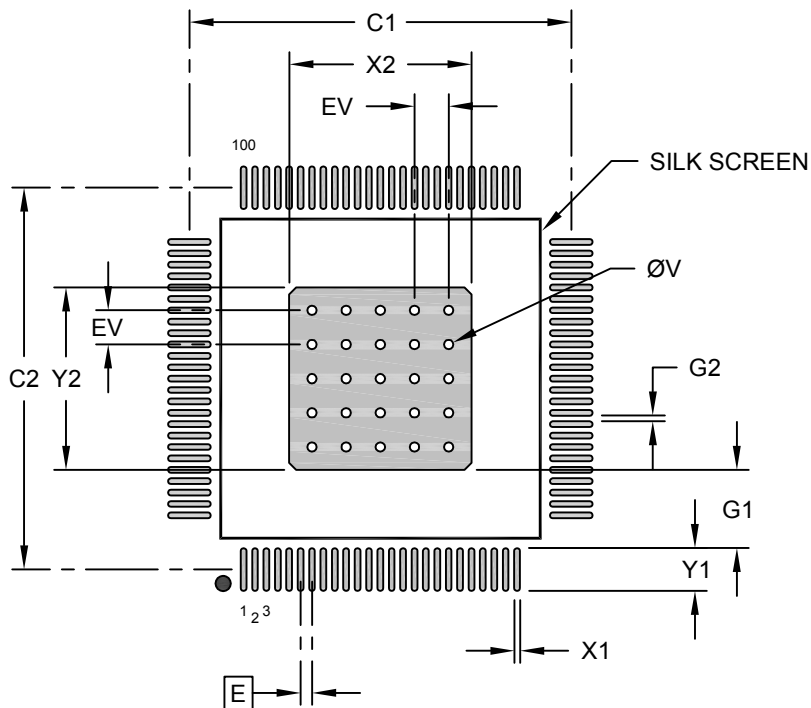


100-Lead Plastic Thin Quad Flatpack (4JB) - 12x12x1.0 mm Body [TQFP] With 6.3 mm Grooved Exposed Pad

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

| | | Units | MILLIMETERS | | |
|----------------------------------|----|-------|-------------|-------|------|
| Dimension Limits | | | MIN | NOM | MAX |
| Contact Pitch | E | | 0.40 BSC | | |
| Center Pad Width | X2 | | | | 6.40 |
| Center Pad Length | Y2 | | | | 6.40 |
| Contact Pad Spacing | C1 | | | 13.40 | |
| Contact Pad Spacing | C2 | | | 13.40 | |
| Contact Pad Width (X100) | X1 | | | | 0.20 |
| Contact Pad Length (X100) | Y1 | | | | 1.50 |
| Contact Pad to Center Pad | G1 | | 2.75 | | |
| Contact Pad to Contact Pad (X96) | G2 | | 0.20 | | |
| Thermal Via Diameter | V | | | 0.33 | |
| Thermal Via Pitch | EV | | | 1.20 | |

Notes:

- Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
- For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process